

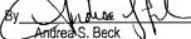
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Mail Stop Issue Fee, Commissioner for Patents, P.O. Box 1450, Alexandria,  
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PATENT

Attorney Docket No.: 018865-  
012810US

on January 26, 2007

TOWNSEND and TOWNSEND and CREW LLP

By   
Andrea S. Beck

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Romel N. Manatad, et al.

Application No.: 10/772,064

Filed: February 3, 2004

For: Alternative Flip Chip in Leaded  
Molded Package Design and Method  
for Manufacture

Customer No.: 020350

Confirmation No.: 4533

Examiner: William M. Brewster

Art Unit: 2823

LETTER TO OFFICIAL DRAFTSPERSON

Mail Stop Issue Fee  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Notice of Allowance dated December 21, 2006, applicants hereby submit 4 sheets of formal drawings to be made of record in the above-identified case.

Respectfully submitted,

  
Patrick R. Jewik  
Reg. No. 40,456

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